

Appl. No. : 10/092,966
Filed : March 5, 2002

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~.

1 (currently amended): A method for manufacturing a ceramic green sheet comprising steps of:

preparing a carrier sheet comprising a base film and an adhesive layer;

forming a predetermined electrode pattern on said adhesive layer, said adhesive layer being separable from said electrode pattern by being cured with UV; and

applying a ceramic slurry onto (A) said electrode pattern formed on said adhesive layer and (B) an exposed surface of said adhesive layer to form a ceramic binder layer which adheres to said electrode pattern and said exposed surface, thereby forming a flat ceramic green sheet on the carrier sheet.

2 (canceled)

3 (currently amended): A method for manufacturing a ceramic green sheet comprising steps of:

preparing a carrier sheet comprising a base film and an adhesive layer;

forming a predetermined electrode pattern on said adhesive layer, said adhesive layer being separable from said electrode pattern by heating; and

applying a ceramic slurry onto (A) said electrode pattern formed on said adhesive layer and (B) an exposed surface of said adhesive layer to form a ceramic binder layer which adheres to said electrode pattern and said exposed surface, thereby forming a flat ceramic green sheet on the carrier sheet,

wherein the adhesive layer separable by heating comprises thermal expandable fine particles.

4 (previously presented): The method according to Claim 3, wherein a dynamic modulus of elastic of an adhesive forming the adhesive layer separable by heating is in a range of 5×10^3 to 1×10^6 Pa at a temperature of 23 degrees C to 150 degrees C.

5 (currently amended): A method for manufacturing a ceramic green sheet comprising steps of:

preparing a carrier sheet comprising a base film and an adhesive layer;

forming a predetermined electrode pattern on said adhesive layer, said adhesive layer being separable from said electrode pattern by heating; and

applying a ceramic slurry onto (A) said electrode pattern formed on said adhesive layer and (B) an exposed surface of said adhesive layer to form a ceramic binder layer which adheres to said electrode pattern and said exposed surface, thereby forming a flat ceramic green sheet on the carrier sheet,

wherein the adhesive layer separable by heating comprises a side chain crystalline resin.

6 (previously presented): The method according to Claim 5, wherein an adhesive strength to stainless steel of the adhesive layer separable by heating is more than 0.1 N / 20mm at ordinary temperature (23 degrees C) and is no more than 0.1 N / 20mm when heated.

7 (previously presented): The method according to Claim 1, wherein an adhesive strength at ordinary temperature (23 degrees C) to stainless steel of the adhesive layer separable by being cured with UV is more than 0.1 N / 20mm before UV irradiation and no more than 0.1N / 20mm after UV irradiation.

8 (previously presented): A method for manufacturing a multilayer ceramic electronic component comprising steps of:

manufacturing a ceramic green sheet by the method according to Claim 1;

laminating the ceramic green sheet onto other ceramic green sheets; and separating a carrier sheet from the ceramic green sheet by being irradiated with UV.

9 (previously presented): A carrier sheet for ceramic green sheets used for the method according to Claim 1, said carrier sheet comprising a base film and an adhesive layer separable by being cured with UV on one side of said base film.

10 (previously presented): A multilayer ceramic electronic component obtained by the method according to Claim 8.

11 (previously presented): A carrier sheet for ceramic green sheets used for the method according to Claim 8, said carrier sheet comprising a base film and an adhesive layer separable by being cured with UV on one side of said base film.

12 (previously presented): The method according to Claim 3, wherein a dynamic modulus of elastic of an adhesive forming the adhesive layer separable by heating is in a range of 5×10^4 to 8×10^5 Pa at a temperature of 23 degrees C to 150 degrees C.

13 (previously presented): The method according to Claim 5, wherein an adhesive strength to stainless steel of the adhesive layer separable by heating is more than 0.2 N / 20mm at ordinary temperature (23 degrees C) and is no more than 0.05 N / 20mm when heated.

14 (previously presented): The method according to Claim 1, wherein an adhesive strength at ordinary temperature (23 degrees C) to stainless steel of the adhesive layer separable by being cured with UV is more than 0.2 N / 20mm before UV irradiation and no more than 0.05 N / 20mm after UV irradiation.

15 (previously presented): The method according to Claim 3, wherein the adhesive layer separable by heating foams when heated, and makes separation with ease.

16 (previously presented): The method according to Claim 1, which additionally comprising separating the carrier sheet from the ceramic green sheet by being cured with UV.

17 (previously presented): The method according to Claim 3, which additionally comprising separating the carrier sheet from the ceramic green sheet by heating.

18 (previously presented): The method according to Claim 5, which additionally comprising separating the carrier sheet from the ceramic green sheet by heating.

19 (previously presented): A method for manufacturing a multilayer ceramic electronic component comprising steps of:

- manufacturing a ceramic green sheet by the method according to Claim 3;
- laminating the ceramic green sheet onto other ceramic green sheets; and
- separating a carrier sheet from the ceramic green sheet by heating.

20 (previously presented): A method for manufacturing a multilayer ceramic electronic component comprising steps of:

- manufacturing a ceramic green sheet by the method according to Claim 5;
- laminating the ceramic green sheet onto other ceramic green sheets; and
- separating a carrier sheet from the ceramic green sheet by heating.

21 (previously presented): A carrier sheet for ceramic green sheets used for the method according to Claim 3, said carrier sheet comprising a base film and an adhesive layer separable by heating on one side of said base film, wherein said adhesive layer comprises thermal expandable fine particles.

22 (previously presented): A carrier sheet for ceramic green sheets used for the method according to Claim 5, said carrier sheet comprising a base film and an adhesive layer

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separable by heating on one side of said base film, wherein said adhesive layer comprises a side chain crystalline resin.